

5 é / Descriptions

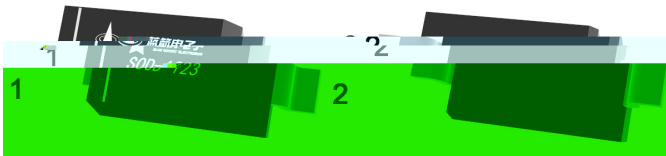
SOD-123 .> // x | 9 8 â 'ož
Zener Diode in a SOD-123 Plastic Package.

α^a / Features

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500mW power dissipation, medium current, automated assembly processes, HF Product.

Đ ÷ / Applications

9 < < ! 8 | 9 è ož
2.4V to 39V wide zener voltage range applications.



PIN1:Cathode PIN2:Anode

, M V / Marking

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See Marking Instructions.

@ f Parameter	... Z Symbol	f › Rating	% y Unit
Forward Voltage (Note 2) I _F =10mA	V _F	0.9	V
Power Dissipation(Note 1)	P _D	500	mW
Typical Thermal Resistance Junction to Ambient(Note 1)	R _{JA}	305	/W
Junction and Storage Temperature Range	T _j , T _{stg}	-65 150	

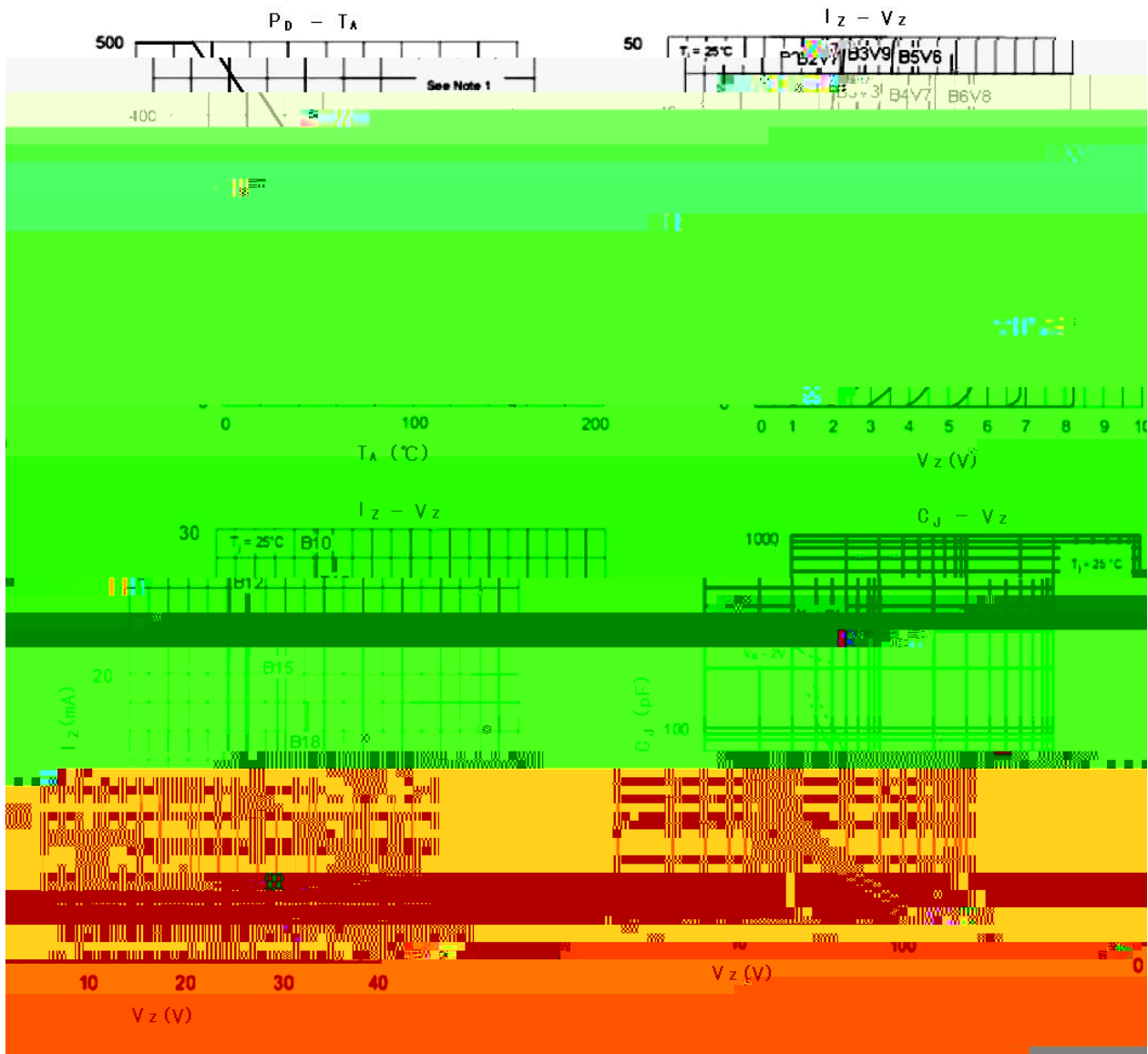
Type Number	Marking Code	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current	
		V _z @ I _{ZT}			I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	I _R	@ V _R
		Nom (V)	Min (V)	Max (V)	mA			mA	A	V

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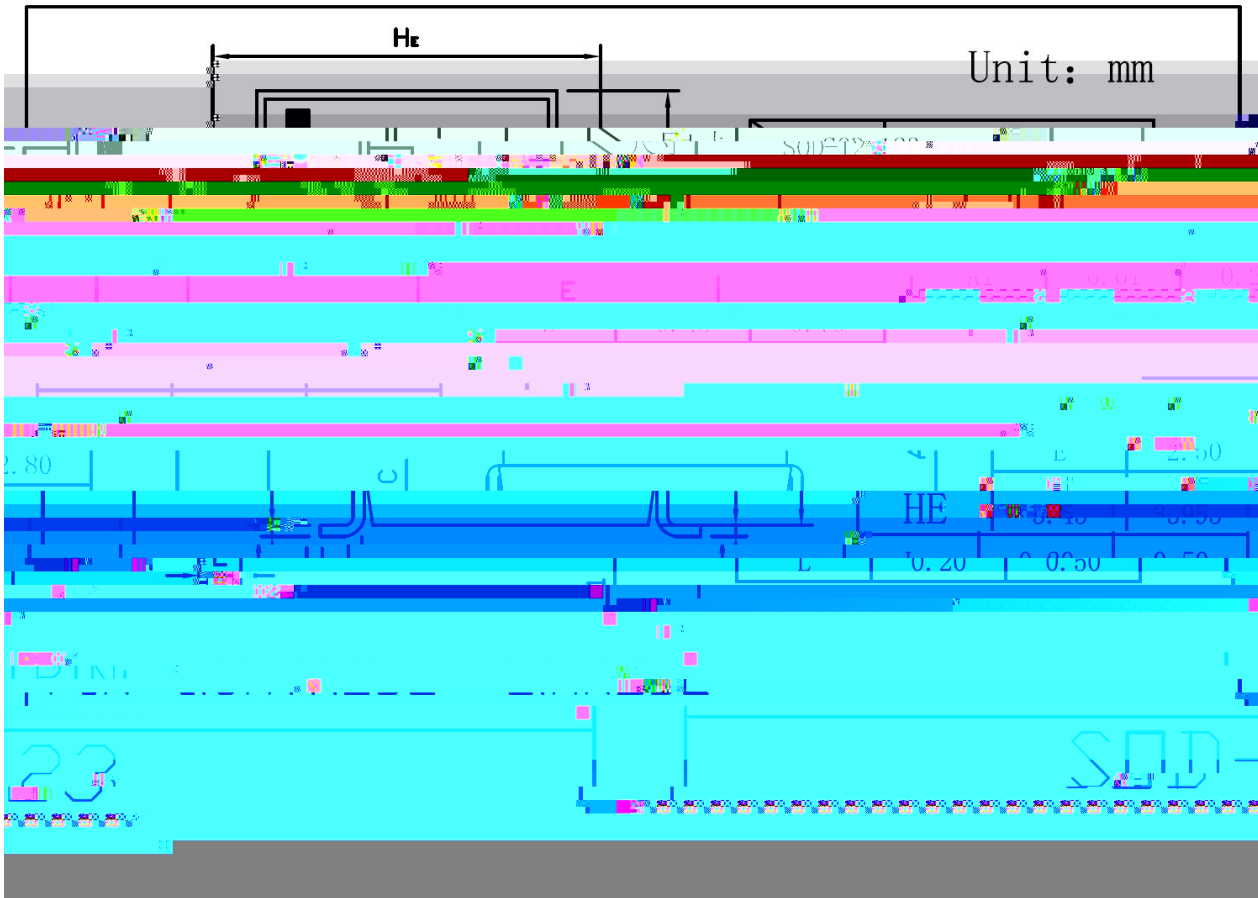
Notes:

1. Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad areas 25mm².
2. Short duration test pulse used to minimize self-heating effect.
3. f = 1kHz.

Electrical Characteristic Curve



Ø □ =) φ / Package Dimensions



BZT52BXXX

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- 1. Preheating: 150~180 °C, Time: 60~90sec;
- 2. Peak Temp.: 245 °C, Duration: 5 r 0.5sec;
- 3. Cooling Speed: 2~10 °C/sec.

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ÂD /Cã p ~ »] / Resistance to Soldering Heat Test Conditions

“† y 260 r5 - ž • y 10 r1 sec. Temp.: 260±5 Time: 10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type	Units	Dimension	(unit μm ³)
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